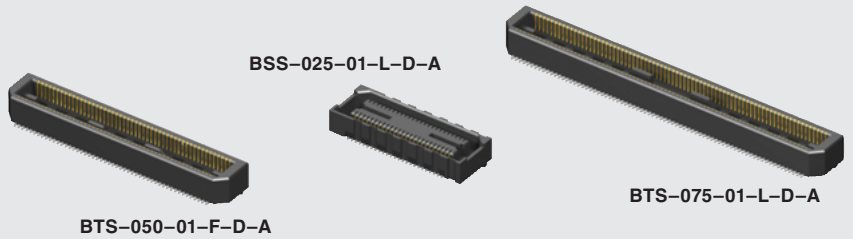




(0,635 mm) .025"



BTS, BSS SERIES

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTS or www.samtec.com?BSS

Insulator Material: Liquid Crystal Polymer
Terminal Material (BTS): Phosphor Bronze
Contact Material (BSS): Phosphor Bronze
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Current Rating: 1.8 A per pin (1 pin powered per row)
Operating Temp Range: -55°C to +125°C
RoHS Compliant: Yes

Processing:
Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max
Board Stacking: For applications requiring more than two connectors per board or 100 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5,00) .197

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- 30µ" (0,76 µm) Gold
 - Other platings
 - Other positions
- Contact Samtec.

OTHER SOLUTIONS

Edge Mount capability. Call for availability.



Note: Some lengths, styles and options are non-standard, non-returnable.

BTS — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with: **BSS**

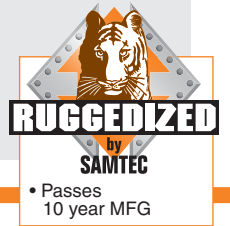
-025, -050, -075, -100

-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-K
= (7,00 mm) .275" DIA Polyimide Film Pick & Place Pad

-TR
= Tape & Reel (-100 positions maximum)



BSS — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with: **BTS**

-025, -050, -075, -100

-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-TR
= Tape & Reel (-100 positions maximum)